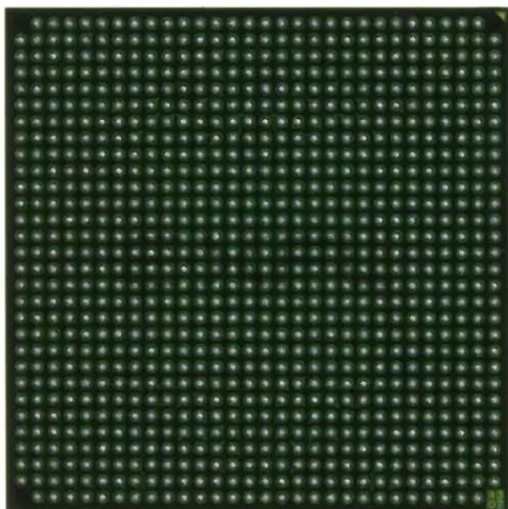




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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	3424
Number of Logic Elements/Cells	30816
Total RAM Bits	2506752
Number of I/O	556
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FCBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp30-6ffg896c



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description

DS083 (v5.0) June 21, 2011

Product Specification

Virtex-II Pro⁽¹⁾ Array Functional Description

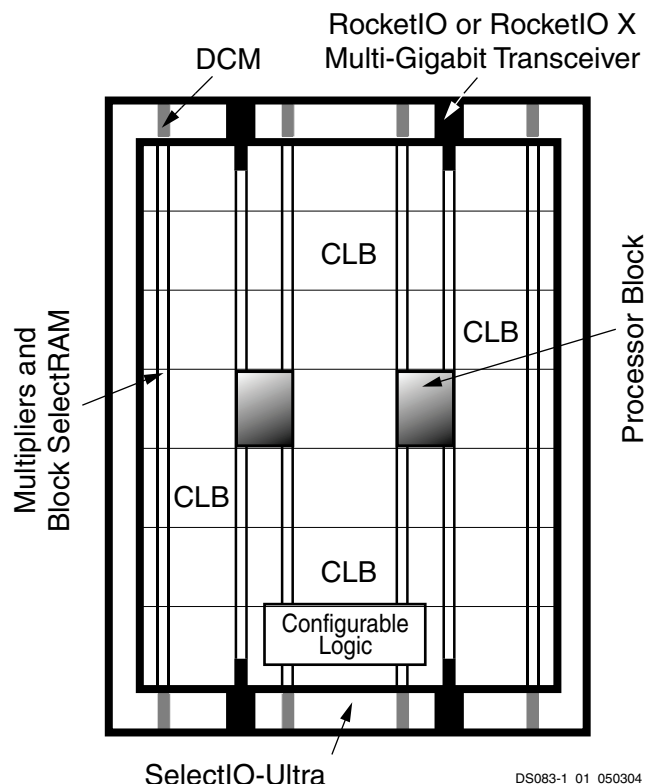


Figure 1: Virtex-II Pro Generic Architecture Overview

This module describes the following Virtex™-II Pro functional components, as shown in **Figure 1**:

- Embedded RocketIO™ (up to 3.125 Gb/s) or RocketIO X (up to 6.25 Gb/s) Multi-Gigabit Transceivers (MGTs)
- Processor blocks with embedded IBM PowerPC™ 405 RISC CPU core (PPC405) and integration circuitry.
- FPGA fabric based on Virtex-II architecture.

Virtex-II Pro User Guides

Virtex-II Pro User Guides cover theory of operation in more detail, and include implementation details, primitives and attributes, command/instruction sets, and many HDL code examples where appropriate. All parameter specifications are given only in **Module 3** of this Data Sheet.

These User Guides are available:

- For detailed descriptions of PPC405 embedded core programming models and internal core operations, see [PowerPC Processor Reference Guide](#) and [PowerPC 405 Processor Block Reference Guide](#).
- For detailed RocketIO transceiver digital/analog design considerations, see [RocketIO Transceiver User Guide](#).
- For detailed RocketIO X transceiver digital/analog design considerations, see [RocketIO X Transceiver User Guide](#).
- For detailed descriptions of the FPGA fabric (CLB, IOB, DCM, etc.), see [Virtex-II Pro Platform FPGA User Guide](#).

All of the documents above, as well as a complete listing and description of Xilinx-developed Intellectual Property cores for Virtex-II Pro, are available on the Xilinx website.

Contents of This Module

- [Functional Description: RocketIO X Multi-Gigabit Transceiver \(MGT\)](#)
- [Functional Description: RocketIO Multi-Gigabit Transceiver \(MGT\)](#)
- [Functional Description: Processor Block](#)
- [Functional Description: Embedded PowerPC 405 Core](#)
- [Functional Description: FPGA](#)
- [Revision History](#)

Virtex-II Pro Compared to Virtex-II Devices

Virtex-II Pro devices are built on the Virtex-II FPGA architecture. Most FPGA features are identical to Virtex-II devices. Major differences are described below:

- The Virtex-II Pro FPGA family is the first to incorporate embedded PPC405 and RocketIO/RocketIO X cores.
- V_{CCAUX} , the auxiliary supply voltage, is 2.5V instead of 3.3V as for Virtex-II devices. Advanced processing at 0.13 μ m has resulted in a smaller die, faster speed, and lower power consumption.
- Virtex-II Pro devices are neither bitstream-compatible nor pin-compatible with Virtex-II devices. However, Virtex-II designs can be compiled into Virtex-II Pro devices.
- On-chip input LVDS differential termination is available.
- SSTL3, AGP-2X/AGP, LVPECL_33, LVDS_33, and LVDSEXT_33 standards are not supported.
- The open-drain output pin TDO does not have an internal pull-up resistor.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

Table 9: Supported Differential Signal I/O Standards

I/O Standard	Output V _{CCO}	Input V _{CCO}	Input V _{REF}	Output V _{OD}
LDT_25	2.5	N/R	N/R	0.500 – 0.740
LVDS_25	2.5	N/R	N/R	0.247 – 0.454
LVDSEXT_25	2.5	N/R	N/R	0.440 – 0.820
BLVDS_25	2.5	N/R	N/R	0.250 – 0.450
ULVDS_25	2.5	N/R	N/R	0.500 – 0.740
LVPECL_25	2.5	N/R	N/R	0.345 – 1.185
LDT_25_DT ⁽¹⁾	2.5	2.5	N/R	0.500 – 0.740
LVDS_25_DT ⁽¹⁾	2.5	2.5	N/R	0.247 – 0.454
LVDSEXT_25_DT ⁽¹⁾	2.5	2.5	N/R	0.330 – 0.700
ULVDS_25_DT ⁽¹⁾	2.5	2.5	N/R	0.500 – 0.740

Notes:

1. These standards support on-chip 100Ω termination.
2. N/R = no requirement.

Table 10: Supported DCI I/O Standards

I/O Standard	Output V _{CCO}	Input V _{CCO}	Input V _{REF}	Termination Type
LVDCI_33 ⁽¹⁾	3.3	3.3	N/R	Series
LVDCI_25	2.5	2.5	N/R	Series
LVDCI_DV2_25	2.5	2.5	N/R	Series
LVDCI_18	1.8	1.8	N/R	Series
LVDCI_DV2_18	1.8	1.8	N/R	Series
LVDCI_15	1.5	1.5	N/R	Series
LVDCI_DV2_15	1.5	1.5	N/R	Series
GTL_DCI	1.2	1.2	0.8	Single
GTLP_DCI	1.5	1.5	1.0	Single
HSTL_I_DCI	1.5	1.5	0.75	Split
HSTL_II_DCI	1.5	1.5	0.75	Split
HSTL_III_DCI	1.5	1.5	0.9	Single
HSTL_IV_DCI	1.5	1.5	0.9	Single
HSTL_I_DCI_18	1.8	1.8	0.9	Split
HSTL_II_DCI_18	1.8	1.8	0.9	Split
HSTL_III_DCI_18	1.8	1.8	1.1	Single
HSTL_IV_DCI_18	1.8	1.8	1.1	Single
SSTL2_I_DCI ⁽²⁾	2.5	2.5	1.25	Split
SSTL2_II_DCI ⁽²⁾	2.5	2.5	1.25	Split
SSTL18_I_DCI ⁽³⁾	1.8	1.8	0.9	Split
SSTL18_II_DCI	1.8	1.8	0.9	Split

Table 10: Supported DCI I/O Standards (Continued)

I/O Standard	Output V _{CCO}	Input V _{CCO}	Input V _{REF}	Termination Type
LVDS_25_DCI	2.5	2.5	N/R	Split
LVDSEXT_25_DCI	2.5	2.5	N/R	Split

Notes:

1. LVDCI_XX is LVCMOS output controlled impedance buffers, matching all or half of the reference resistors.
2. These are SSTL compatible.
3. SSTL18_I is not a JEDEC-supported standard.
4. N/R = no requirement.

Logic Resources

IOB blocks include six storage elements, as shown in Figure 19.

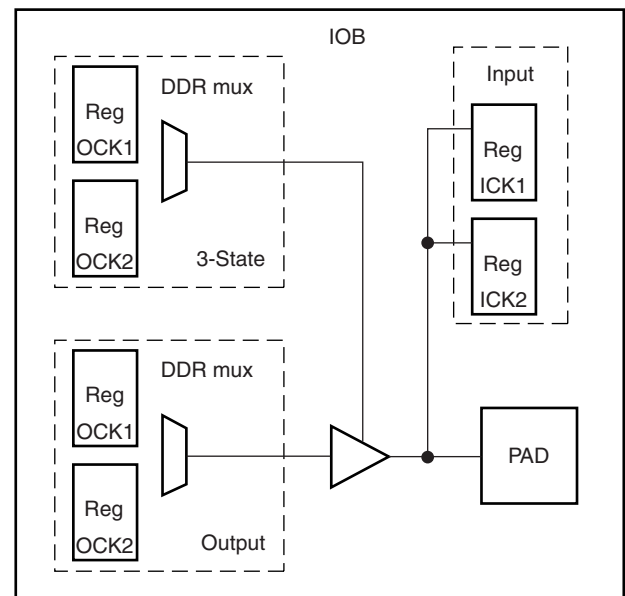


Figure 19: Virtex-II Pro IOB Block

Each storage element can be configured either as an edge-triggered D-type flip-flop or as a level-sensitive latch. On the input, output, and 3-state path, one or two DDR registers can be used.

Double data rate is directly accomplished by the two registers on each path, clocked by the rising edges (or falling edges) from two different clock nets. The two clock signals are generated by the DCM and must be 180 degrees out of phase, as shown in Figure 20. There are two input, output, and 3-state data signals, each being alternately clocked out.

synchronously. The sequence can also be paused at any stage, until lock has been achieved on any or all DCMs, as well as DCI.

Readback

In this mode, configuration data from the Virtex-II Pro FPGA device can be read back. Readback is supported only in the SelectMAP (master and slave) and Boundary-Scan mode.

Along with the configuration data, it is possible to read back the contents of all registers, distributed SelectRAM+, and block RAM resources. This capability is used for real-time debugging. For more detailed configuration information, see the *Virtex-II Pro Platform FPGA User Guide*.

Bitstream Encryption

Virtex-II Pro devices have an on-chip decryptor using one or two sets of three keys for triple-key Data Encryption Standard (DES) operation. Xilinx software tools offer an optional encryption of the configuration data (bitstream) with a triple-key DES determined by the designer.

The keys are stored in the FPGA by JTAG instruction and retained by a battery connected to the V_{BATT} pin, when the device is not powered. Virtex-II Pro devices can be config-

ured with the corresponding encrypted bitstream, using any of the configuration modes described previously.

A detailed description of how to use bitstream encryption is provided in the [Virtex-II Pro Platform FPGA User Guide](#). Your local FAE can also provide specific information on this feature.

Partial Reconfiguration

Partial reconfiguration of Virtex-II Pro devices can be accomplished in either Slave SelectMAP mode or Boundary-Scan mode. Instead of resetting the chip and doing a full configuration, new data is loaded into a specified area of the chip, while the rest of the chip remains in operation. Data is loaded on a column basis, with the smallest load unit being a configuration “frame” of the bitstream (device size dependent).

Partial reconfiguration is useful for applications that require different designs to be loaded into the same area of a chip, or that require the ability to change portions of a design without having to reset or reconfigure the entire chip.

For more information on Partial Reconfiguration in Virtex-II Pro devices, please refer to Xilinx Application Note [XAPP290](#), *Two Flows for Partial Reconfiguration*.

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
06/13/02	2.0	New Virtex-II Pro family members. New timing parameters per speedsfile v1.62 .
09/03/02	2.1	- Revised Reset and Power sections. - Updated Table 8, which lists compatible input standards. [Table deleted in v2.6.] - Added Figure 28, Figure 29, and Figure 30, which provide examples illustrating the use of I/O standards.
09/27/02	2.2	- In section RocketIO Overview, corrected max number of MGTs from 16 to 24. - In section Input/Output Blocks (IOBs), added references to XAPP653 regarding implementation of 3.3V I/O standards.
11/20/02	2.3	Table 8: Added rows for LVTTTL, LVCMOS33, and PCI-X. Table 8: Added LVTTTL and LVCMOS33 to compatible 3.3V cells. [Table deleted in v2.6.] Table 33: Correct bitstream lengths.
12/03/02	2.4	Added mention of LVTTTL and PCI with respect to SelectIO-Ultra configurations. See section Input/Output Individual Options and Figure 22.
01/20/03	2.5	- Added qualification to features vs. Virtex-II (open-drain output pin TDO does not have internal pull-up resistor) - Table 7: Added HSTL18 (I, II, III, & IV) and HSTL18_DCI (I,II, III & IV) to 1.8V VCCO row. [Table deleted in v2.6.] - Table 8: Numerous revisions. [Table deleted in v2.6.]

Table 35: IOB Input Switching Characteristics (Continued)

			Speed Grade			
Description	Symbol	Device	-7	-6	-5	Units
Setup and Hold Times With Respect to Clock at IOB Input Register						
Pad, no delay	T_{IOICK}/T_{IOICKP}	All	0.84/–0.61	0.86/–0.63	0.90/–0.67	ns, min
Pad, with delay	$T_{IOICKD}/T_{IOICKPD}$	XC2VP2	2.28/–1.89	2.60/–2.15	2.95/–2.43	ns, max
		XC2VP4	2.55/–2.10	2.87/–2.36	3.21/–2.65	ns, max
		XC2VP7	2.48/–2.05	2.82/–2.32	3.15/–2.60	ns, max
		XC2VP20	2.63/–2.05	3.02/–2.35	3.40/–2.66	ns, max
		XC2VPX20	2.63/–2.05	3.02/–2.35	3.40/–2.66	ns, max
		XC2VP30	2.67/–2.07	3.09/–2.42	3.49/–2.73	ns, max
		XC2VP40	3.28/–2.56	3.61/–2.83	4.01/–3.15	ns, max
		XC2VP50	3.84/–3.02	4.08/–3.21	4.42/–3.48	ns, max
		XC2VP70	3.98/–3.13	4.23/–3.33	4.55/–3.58	ns, max
		XC2VPX70	3.98/–3.13	4.23/–3.33	4.55/–3.58	ns, max
	XC2VP100	N/A	6.48/–5.13	7.04/–5.57	ns, max	
ICE input	$T_{IOICECK}/T_{IOCKICE}$	All	0.39/ 0.01	0.44/ 0.01	0.49/ 0.01	ns, min
SR input (IFF, synchronous)	$T_{IOSRCKI}$	All	0.52	0.57	0.75	ns, min
Set/Reset Delays						
SR input to IQ (asynchronous)	T_{IOSRIQ}	All	1.13	1.27	1.42	ns, max
GSR to output IQ	T_{GSRQ}	All	5.87	6.75	7.43	ns, max

Notes:

- Input timing for LVCMOS25 is measured at 1.25V. For other I/O standards, see [Table 39](#).

I/O Standard Adjustment Measurement Methodology

Input Delay Measurements

Table 39 shows the test setup parameters used for measuring Input standard adjustments (see Table 36, page 25).

Table 39: Input Delay Measurement Methodology

Description	IOSTANDARD Attribute	$V_L^{(1,2)}$	$V_H^{(1,2)}$	$V_{MEAS}^{(1,4,5)}$	$V_{REF}^{(1,3,5)}$
LVTTTL (Low-Voltage Transistor-Transistor Logic)	LVTTTL	0	3.3	1.65	—
LVC MOS (Low-Voltage CMOS), 3.3V	LVC MOS33	0	3.3	1.65	—
LVC MOS, 2.5V	LVC MOS25	0	2.5	1.25	—
LVC MOS, 1.8V	LVC MOS18	0	1.8	0.9	—
LVC MOS, 1.5V	LVC MOS15	0	1.5	0.75	—
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3	Per PCI Specification			—
PCI, 66 MHz, 3.3V	PCI66_3	Per PCI Specification			—
PCI-X, 133 MHz, 3.3V	PCIX	Per PCI-X Specification			—
GTL (Gunning Transceiver Logic)	GTL	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	0.80
GTL Plus	GTLP	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	1.0
HSTL (High-Speed Transceiver Logic), Class I & II	HSTL_I, HSTL_II	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.75
HSTL, Class III & IV	HSTL_III, HSTL_IV	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
HSTL, Class I & II, 1.8V	HSTL_I_18, HSTL_II_18	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
HSTL, Class III & IV, 1.8V	HSTL_III_18, HSTL_IV_18	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	1.08
SSTL (Stub Terminated Tnschr Logic), Class I & II, 2.5V	SSTL2_I, SSTL2_II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	V_{REF}	1.25
SSTL, Class I & II, 1.8V	SSTL18_I, SSTL18_II	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.9
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	$1.2 - 0.125$	$1.2 + 0.125$	1.2	
LVDSEXT (LVDS Extended Mode), 2.5V	LVDSEXT_25	$1.2 - 0.125$	$1.2 + 0.125$	1.2	
ULVDS (Ultra LVDS), 2.5V	ULVDS_25	$0.6 - 0.125$	$0.6 + 0.125$	0.6	
LDT (HyperTransport), 2.5V	LDT_25	$0.6 - 0.125$	$0.6 + 0.125$	0.6	
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V	LVPECL_25	$1.15 - 0.3$	$1.15 + 0.3$	1.15	

Notes:

1. Input delay measurement methodology parameters for LVDCI and HSLVDCI are the same as for LVC MOS standards of the same voltage. Parameters for all other DCI standards are the same as for the corresponding non-DCI standards.
2. Input waveform switches between V_L and V_H .
3. Measurements are made at typical, minimum, and maximum V_{REF} values. Reported delays reflect worst case of these measurements. V_{REF} values listed are typical. See [Virtex-II Pro Platform FPGA User Guide](#) for min/max specifications.
4. Input voltage level from which measurement starts.
5. Note that this is an input voltage reference that bears no relation to the V_{REF} / V_{MEAS} parameters found in IBIS models and/or noted in Figure 6.

Multiplier Switching Characteristics

Table 45: Multiplier Switching Characteristics

		Speed Grade			
Description	Symbol	-7	-6	-5	Units
Propagation Delay to Output Pin					
Input to Pin35	T _{MULT_P35}	4.08	4.64	5.19	ns, max
Input to Pin34	T _{MULT_P34}	3.99	4.55	5.09	ns, max
Input to Pin33	T _{MULT_P33}	3.90	4.45	4.99	ns, max
Input to Pin32	T _{MULT_P32}	3.80	4.36	4.88	ns, max
Input to Pin31	T _{MULT_P31}	3.71	4.27	4.78	ns, max
Input to Pin30	T _{MULT_P30}	3.62	4.17	4.67	ns, max
Input to Pin29	T _{MULT_P29}	3.53	4.08	4.57	ns, max
Input to Pin28	T _{MULT_P28}	3.43	3.99	4.46	ns, max
Input to Pin27	T _{MULT_P27}	3.34	3.89	4.36	ns, max
Input to Pin26	T _{MULT_P26}	3.25	3.80	4.26	ns, max
Input to Pin25	T _{MULT_P25}	3.16	3.71	4.15	ns, max
Input to Pin24	T _{MULT_P24}	3.06	3.61	4.05	ns, max
Input to Pin23	T _{MULT_P23}	2.97	3.52	3.94	ns, max
Input to Pin22	T _{MULT_P22}	2.88	3.43	3.84	ns, max
Input to Pin21	T _{MULT_P21}	2.79	3.34	3.73	ns, max
Input to Pin20	T _{MULT_P20}	2.70	3.24	3.63	ns, max
Input to Pin19	T _{MULT_P19}	2.60	3.15	3.53	ns, max
Input to Pin18	T _{MULT_P18}	2.51	3.06	3.42	ns, max
Input to Pin17	T _{MULT_P17}	2.42	2.96	3.32	ns, max
Input to Pin16	T _{MULT_P16}	2.34	2.86	3.21	ns, max
Input to Pin15	T _{MULT_P15}	2.27	2.76	3.09	ns, max
Input to Pin14	T _{MULT_P14}	2.19	2.67	2.98	ns, max
Input to Pin13	T _{MULT_P13}	2.12	2.57	2.87	ns, max
Input to Pin12	T _{MULT_P12}	2.04	2.47	2.76	ns, max
Input to Pin11	T _{MULT_P11}	1.96	2.37	2.65	ns, max
Input to Pin10	T _{MULT_P10}	1.89	2.27	2.54	ns, max
Input to Pin9	T _{MULT_P9}	1.81	2.17	2.43	ns, max
Input to Pin8	T _{MULT_P8}	1.74	2.07	2.32	ns, max
Input to Pin7	T _{MULT_P7}	1.66	1.97	2.21	ns, max
Input to Pin6	T _{MULT_P6}	1.59	1.87	2.09	ns, max
Input to Pin5	T _{MULT_P5}	1.51	1.77	1.98	ns, max
Input to Pin4	T _{MULT_P4}	1.44	1.67	1.87	ns, max
Input to Pin3	T _{MULT_P3}	1.36	1.57	1.76	ns, max
Input to Pin2	T _{MULT_P2}	1.28	1.47	1.65	ns, max
Input to Pin1	T _{MULT_P1}	1.21	1.37	1.54	ns, max
Input to Pin0	T _{MULT_P0}	1.13	1.27	1.43	ns, max

Output Clock Jitter

Table 59: Output Clock Jitter

Description	Symbol	Constraints	Speed Grade			Units
			–7	–6	–5	
Clock Synthesis Period Jitter						
CLK0	CLKOUT_PER_JITT_0		±100	±100	±100	ps
CLK90	CLKOUT_PER_JITT_90		±150	±150	±150	ps
CLK180	CLKOUT_PER_JITT_180		±150	±150	±150	ps
CLK270	CLKOUT_PER_JITT_270		±150	±150	±150	ps
CLK2X, CLK2X180	CLKOUT_PER_JITT_2X		±200	±200	±200	ps
CLKDV (integer division)	CLKOUT_PER_JITT_DV1		±150	±150	±150	ps
CLKDV (non-integer division)	CLKOUT_PER_JITT_DV2		±300	±300	±300	ps
CLKFX, CLKFX180	CLKOUT_PER_JITT_FX		Note (1)	Note (1)	Note (1)	ps

Notes:

1. Use the **Jitter Calculator** on the Xilinx website (http://www.xilinx.com/applications/web_ds_v2/jitter_calc.htm) for CLKFX and CLKFX180 output jitter.

Output Clock Phase Alignment

Table 60: Output Clock Phase Alignment

Description	Symbol	Constraints	Speed Grade			Units
			–7	–6	–5	
Phase Offset Between CLKIN and CLKFB						
CLKIN/CLKFB	CLKIN_CLKFB_PHASE		±50	±50	±50	ps
Phase Offset Between Any DCM Outputs						
All CLK* outputs	CLKOUT_PHASE		±140	±140	±140	ps
Duty Cycle Precision						
DLL outputs ⁽¹⁾	CLKOUT_DUTY_CYCLE_DLL ⁽²⁾		±150	±150	±150	ps
CLKFX outputs	CLKOUT_DUTY_CYCLE_FX		±100	±100	±100	ps

Notes:

1. “DLL outputs” is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. CLKOUT_DUTY_CYCLE_DLL applies to the 1X clock outputs (CLK0, CLK90, CLK180, and CLK270) only if DUTY_CYCLE_CORRECTION = TRUE.
3. Specification also applies to PSCLK.

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
4	IO_L54N_4	V15			
4	IO_L54P_4	W15			
4	IO_L55N_4	Y15			
4	IO_L55P_4	AA15			
4	IO_L57N_4	AB15			
4	IO_L57P_4/VREF_4	AA14			
4	IO_L67N_4	AC15			
4	IO_L67P_4	AD15			
4	IO_L69N_4	V14			
4	IO_L69P_4/VREF_4	W14			
4	IO_L74N_4/GCLK3S	AB14			
4	IO_L74P_4/GCLK2P	AC14			
4	IO_L75N_4/GCLK1S	AD14			
4	IO_L75P_4/GCLK0P	AE14			
5	IO_L75N_5/GCLK7S	AE13			
5	IO_L75P_5/GCLK6P	AD13			
5	IO_L74N_5/GCLK5S	AC13			
5	IO_L74P_5/GCLK4P	AB13			
5	IO_L69N_5/VREF_5	W13			
5	IO_L69P_5	V13			
5	IO_L67N_5	AD12			
5	IO_L67P_5	AC12			
5	IO_L57N_5/VREF_5	AA13			
5	IO_L57P_5	AB12			
5	IO_L55N_5	AA12			
5	IO_L55P_5	Y12			
5	IO_L54N_5	W12			
5	IO_L54P_5	V12			
5	IO_L53_5/No_Pair	AA11			
5	IO_L50_5/No_Pair	Y11			
5	IO_L49N_5	AD10			
5	IO_L49P_5	AC10			
5	IO_L48N_5	AB11			
5	IO_L48P_5	AB10			

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
0	IO_L01N_0/VRP_0		E25			
0	IO_L01P_0/VRN_0		E24			
0	IO_L02N_0		F24			
0	IO_L02P_0		F23			
0	IO_L03N_0		E23			
0	IO_L03P_0/VREF_0		E22			
0	IO_L05_0/No_Pair		G23			
0	IO_L06N_0		H22			
0	IO_L06P_0		G22			
0	IO_L07N_0		F22			
0	IO_L07P_0		F21			
0	IO_L08N_0		D24			
0	IO_L08P_0		C24			
0	IO_L09N_0		H21			
0	IO_L09P_0/VREF_0		G21			
0	IO_L37N_0		E21			
0	IO_L37P_0		D21			
0	IO_L38N_0		D23			
0	IO_L38P_0		C23			
0	IO_L39N_0		H20			
0	IO_L39P_0		G20			
0	IO_L43N_0		E20			
0	IO_L43P_0		D20			
0	IO_L44N_0		B23			
0	IO_L44P_0		A23			
0	IO_L45N_0		H19			
0	IO_L45P_0/VREF_0		G19			
0	IO_L46N_0		E19	NC		
0	IO_L46P_0		E18	NC		
0	IO_L47N_0		C22	NC		
0	IO_L47P_0		B22	NC		
0	IO_L48N_0		F20	NC		
0	IO_L48P_0		F19	NC		
0	IO_L49N_0		G17	NC		
0	IO_L49P_0		F17	NC		
0	IO_L50_0/No_Pair		B21	NC		

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
1	IO_L54N_1		G13	NC		
1	IO_L54P_1		H13	NC		
1	IO_L53_1/No_Pair		A10	NC		
1	IO_L50_1/No_Pair		B10	NC		
1	IO_L49N_1		F14	NC		
1	IO_L49P_1		G14	NC		
1	IO_L48N_1		F12	NC		
1	IO_L48P_1		F11	NC		
1	IO_L47N_1		B9	NC		
1	IO_L47P_1		C9	NC		
1	IO_L46N_1		E13	NC		
1	IO_L46P_1		E12	NC		
1	IO_L45N_1/VREF_1		G12			
1	IO_L45P_1		H12			
1	IO_L44N_1		A8			
1	IO_L44P_1		B8			
1	IO_L43N_1		D11			
1	IO_L43P_1		E11			
1	IO_L39N_1		G11			
1	IO_L39P_1		H11			
1	IO_L38N_1		C8			
1	IO_L38P_1		D8			
1	IO_L37N_1		D10			
1	IO_L37P_1		E10			
1	IO_L09N_1/VREF_1		G10			
1	IO_L09P_1		H10			
1	IO_L08N_1		C7			
1	IO_L08P_1		D7			
1	IO_L07N_1		F10			
1	IO_L07P_1		F9			
1	IO_L06N_1		G9			
1	IO_L06P_1		H9			
1	IO_L05_1/No_Pair		G8			
1	IO_L03N_1/VREF_1		E9			
1	IO_L03P_1		E8			
1	IO_L02N_1		F8			

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
5	IO_L48N_5		AH20	NC		
5	IO_L48P_5		AH21	NC		
5	IO_L47N_5		AE19	NC		
5	IO_L47P_5		AE20	NC		
5	IO_L46N_5		AD18	NC		
5	IO_L46P_5		AC18	NC		
5	IO_L45N_5/VREF_5		AJ22			
5	IO_L45P_5		AH22			
5	IO_L44N_5		AE21			
5	IO_L44P_5		AE22			
5	IO_L43N_5		AD19			
5	IO_L43P_5		AC19			
5	IO_L39N_5		AG21			
5	IO_L39P_5		AF21			
5	IO_L38N_5		AF22			
5	IO_L38P_5		AF23			
5	IO_L37N_5		AD20			
5	IO_L37P_5		AC20			
5	IO_L09N_5/VREF_5		AK23			
5	IO_L09P_5		AJ23			
5	IO_L08N_5		AE23			
5	IO_L08P_5		AE24			
5	IO_L07N_5/VREF_5		AD21			
5	IO_L07P_5		AC21			
5	IO_L06N_5/VRP_5		AH23			
5	IO_L06P_5/VRN_5		AG23			
5	IO_L05_5/No_Pair		AD23			
5	IO_L03N_5/D4		AH24			
5	IO_L03P_5/D5		AG24			
5	IO_L02N_5/D6		AD22			
5	IO_L02P_5/D7		AC22			
5	IO_L01N_5/RDWR_B		AF24			
5	IO_L01P_5/CS_B		AG25			
6	IO_L01P_6/VRN_6		AK28			
6	IO_L01N_6/VRP_6		AJ28			

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
7	IO_L54N_7		L26			
7	IO_L53P_7		N26			
7	IO_L53N_7		N25			
7	IO_L52P_7		M30			
7	IO_L52N_7/VREF_7		L30			
7	IO_L51P_7		K28			
7	IO_L51N_7		K27			
7	IO_L50P_7		N24			
7	IO_L50N_7		N23			
7	IO_L49P_7		L29			
7	IO_L49N_7		K29			
7	IO_L48P_7		J28			
7	IO_L48N_7		J27			
7	IO_L47P_7		M26			
7	IO_L47N_7		M25			
7	IO_L46P_7		K30			
7	IO_L46N_7/VREF_7		J30			
7	IO_L45P_7		K26			
7	IO_L45N_7		K25			
7	IO_L44P_7		M24			
7	IO_L44N_7		M23			
7	IO_L43P_7		J29			
7	IO_L43N_7		H29			
7	IO_L42P_7		H28	NC		
7	IO_L42N_7		H27	NC		
7	IO_L41P_7		L24	NC		
7	IO_L41N_7		L23	NC		
7	IO_L40P_7		G30	NC		
7	IO_L40N_7/VREF_7		G29	NC		
7	IO_L39P_7		G28	NC		
7	IO_L39N_7		G27	NC		
7	IO_L38P_7		J26	NC		
7	IO_L38N_7		J25	NC		
7	IO_L37P_7		F30	NC		
7	IO_L37N_7		F29	NC		
7	IO_L36P_7		F28	NC		

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
2	IO_L05N_2	J8				
2	IO_L05P_2	J7				
2	IO_L06N_2	F5				
2	IO_L06P_2	F4				
2	IO_L15N_2	G4	NC			
2	IO_L15P_2	G3	NC			
2	IO_L16N_2/VREF_2	G6	NC			
2	IO_L16P_2	G5	NC			
2	IO_L17N_2	F2	NC			
2	IO_L17P_2	F1	NC			
2	IO_L18N_2	L10	NC			
2	IO_L18P_2	L9	NC			
2	IO_L19N_2	H6	NC			
2	IO_L19P_2	H5	NC			
2	IO_L20N_2	G2	NC			
2	IO_L20P_2	G1	NC			
2	IO_L21N_2	J6	NC			
2	IO_L21P_2	J5	NC			
2	IO_L22N_2/VREF_2	J4	NC			
2	IO_L22P_2	J3	NC			
2	IO_L23N_2	K8	NC			
2	IO_L23P_2	K7	NC			
2	IO_L24N_2	H4	NC			
2	IO_L24P_2	H3	NC			
2	IO_L31N_2	H2				
2	IO_L31P_2	H1				
2	IO_L32N_2	M10				
2	IO_L32P_2	M9				
2	IO_L33N_2	K5				
2	IO_L33P_2	K4				
2	IO_L34N_2/VREF_2	J2				
2	IO_L34P_2	K2				
2	IO_L35N_2	L8				
2	IO_L35P_2	L7				
2	IO_L36N_2	L6				
2	IO_L36P_2	L5				
2	IO_L37N_2	K1				
2	IO_L37P_2	L1				

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
4	IO_L27P_4/VREF_4	AL10	NC	NC		
4	IO_L37N_4	AE13				
4	IO_L37P_4	AF13				
4	IO_L38N_4	AG13				
4	IO_L38P_4	AH13				
4	IO_L39N_4	AJ11				
4	IO_L39P_4	AK11				
4	IO_L43N_4	AE14				
4	IO_L43P_4	AF14				
4	IO_L44N_4	AJ13				
4	IO_L44P_4	AK13				
4	IO_L45N_4	AL11				
4	IO_L45P_4/VREF_4	AM11				
4	IO_L46N_4	AE15				
4	IO_L46P_4	AF15				
4	IO_L47N_4	AG14				
4	IO_L47P_4	AH14				
4	IO_L48N_4	AL13				
4	IO_L48P_4	AL12				
4	IO_L49N_4	AD16				
4	IO_L49P_4	AE16				
4	IO_L50_4/No_Pair	AJ14				
4	IO_L53_4/No_Pair	AK14				
4	IO_L54N_4	AM14				
4	IO_L54P_4	AM13				
4	IO_L55N_4	AF16				
4	IO_L55P_4	AG16				
4	IO_L56N_4	AH15				
4	IO_L56P_4	AJ15				
4	IO_L57N_4	AL14				
4	IO_L57P_4/VREF_4	AL15				
4	IO_L67N_4	AD17				
4	IO_L67P_4	AE17				
4	IO_L68N_4	AH16				
4	IO_L68P_4	AJ16				
4	IO_L69N_4	AK16				
4	IO_L69P_4/VREF_4	AL16				
4	IO_L73N_4	AF17				

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	VCCAUX	AP6		
N/A	VCCAUX	F6		
N/A	VCCAUX	AR5		
N/A	VCCAUX	E5		
N/A	VCCAUX	AW2		
N/A	VCCAUX	Y2		
N/A	VCCAUX	A2		
N/A	VCCAUX	AV1		
N/A	VCCAUX	AA1		
N/A	VCCAUX	Y1		
N/A	VCCAUX	W1		
N/A	VCCAUX	B1		
N/A	GND	A3		
N/A	GND	AV2		
N/A	GND	AU2		
N/A	GND	AA2		
N/A	GND	W2		
N/A	GND	C2		
N/A	GND	B2		
N/A	GND	AU1		
N/A	GND	AM1		
N/A	GND	AH1		
N/A	GND	AD1		
N/A	GND	T1		
N/A	GND	M1		
N/A	GND	H1		
N/A	GND	C1		
N/A	GND	AD5		
N/A	GND	T5		
N/A	GND	M5		
N/A	GND	H5		
N/A	GND	AU4		
N/A	GND	AT4		
N/A	GND	D4		
N/A	GND	C4		
N/A	GND	AW3		
N/A	GND	AV3		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GND	AU3		
N/A	GND	AT3		
N/A	GND	D3		
N/A	GND	C3		
N/A	GND	B3		
N/A	GND	AN12		
N/A	GND	G12		
N/A	GND	C12		
N/A	GND	Y10		
N/A	GND	AH9		
N/A	GND	AD9		
N/A	GND	T9		
N/A	GND	M9		
N/A	GND	AU8		
N/A	GND	AN8		
N/A	GND	G8		
N/A	GND	C8		
N/A	GND	Y6		
N/A	GND	AM5		
N/A	GND	AH5		
N/A	GND	T17		
N/A	GND	AT16		
N/A	GND	AN16		
N/A	GND	AJ16		
N/A	GND	AC16		
N/A	GND	AB16		
N/A	GND	AA16		
N/A	GND	Y16		
N/A	GND	W16		
N/A	GND	V16		
N/A	GND	U16		
N/A	GND	L16		
N/A	GND	G16		
N/A	GND	D16		
N/A	GND	AU12		
N/A	GND	AB18		
N/A	GND	AA18		
N/A	GND	Y18		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
1	VCCO_1		D18		
2	VCCO_2		AA15		
2	VCCO_2		AA14		
2	VCCO_2		Y15		
2	VCCO_2		Y14		
2	VCCO_2		Y8		
2	VCCO_2		Y5		
2	VCCO_2		W15		
2	VCCO_2		W14		
2	VCCO_2		V15		
2	VCCO_2		V14		
2	VCCO_2		V3		
2	VCCO_2		U15		
2	VCCO_2		U14		
2	VCCO_2		T15		
2	VCCO_2		T14		
2	VCCO_2		R14		
2	VCCO_2		T9		
2	VCCO_2		P4		
2	VCCO_2		M6		
2	VCCO_2		J3		
2	VCCO_2		F5		
3	VCCO_3		AU5		
3	VCCO_3		AP3		
3	VCCO_3		AL6		
3	VCCO_3		AJ4		
3	VCCO_3		AH14		
3	VCCO_3		AG15		
3	VCCO_3		AG14		
3	VCCO_3		AG9		
3	VCCO_3		AF15		
3	VCCO_3		AF14		
3	VCCO_3		AE15		
3	VCCO_3		AE14		
3	VCCO_3		AE3		
3	VCCO_3		AD15		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
5	VCCO_5		AH22		
6	VCCO_6		AU38		
6	VCCO_6		AP40		
6	VCCO_6		AL37		
6	VCCO_6		AJ39		
6	VCCO_6		AH29		
6	VCCO_6		AG34		
6	VCCO_6		AG29		
6	VCCO_6		AG28		
6	VCCO_6		AF29		
6	VCCO_6		AF28		
6	VCCO_6		AE40		
6	VCCO_6		AE29		
6	VCCO_6		AE28		
6	VCCO_6		AD29		
6	VCCO_6		AD28		
6	VCCO_6		AC38		
6	VCCO_6		AC35		
6	VCCO_6		AC29		
6	VCCO_6		AC28		
6	VCCO_6		AB29		
6	VCCO_6		AB28		
7	VCCO_7		AA29		
7	VCCO_7		AA28		
7	VCCO_7		Y38		
7	VCCO_7		Y35		
7	VCCO_7		Y29		
7	VCCO_7		Y28		
7	VCCO_7		W29		
7	VCCO_7		W28		
7	VCCO_7		V40		
7	VCCO_7		V29		
7	VCCO_7		V28		
7	VCCO_7		U29		
7	VCCO_7		U28		
7	VCCO_7		T34		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
4	IO_L58P_4	AW19	
4	IO_L59N_4	AP19	
4	IO_L59P_4	AN19	
4	IO_L60N_4	BB19	
4	IO_L60P_4	BA19	
4	IO_L64N_4	AU20	
4	IO_L64P_4	AT20	
4	IO_L65N_4	AL21	
4	IO_L65P_4	AL20	
4	IO_L66N_4	BA20	
4	IO_L66P_4/VREF_4	AY20	
4	IO_L67N_4	AR21	
4	IO_L67P_4	AP21	
4	IO_L68N_4	AN20	
4	IO_L68P_4	AM20	
4	IO_L69N_4	AU21	
4	IO_L69P_4/VREF_4	AT21	
4	IO_L73N_4	AW21	
4	IO_L73P_4	AV21	
4	IO_L74N_4/GCLK3S	AN21	
4	IO_L74P_4/GCLK2P	AM21	
4	IO_L75N_4/GCLK1S	BA21	
4	IO_L75P_4/GCLK0P	AY21	
5	IO_L75N_5/GCLK7S	AY22	
5	IO_L75P_5/GCLK6P	BA22	
5	IO_L74N_5/GCLK5S	AM22	
5	IO_L74P_5/GCLK4P	AN22	
5	IO_L73N_5	AV22	
5	IO_L73P_5	AW22	
5	IO_L69N_5/VREF_5	AT22	
5	IO_L69P_5	AU22	
5	IO_L68N_5	AM23	
5	IO_L68P_5	AN23	
5	IO_L67N_5	AP22	
5	IO_L67P_5	AR22	
5	IO_L66N_5/VREF_5	AY23	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	E13	
N/A	GND	A13	
N/A	GND	AD12	
N/A	GND	W12	
N/A	GND	BB9	
N/A	GND	AV9	
N/A	GND	AP9	
N/A	GND	AK9	
N/A	GND	AF9	
N/A	GND	AC9	
N/A	GND	Y9	
N/A	GND	U9	
N/A	GND	N9	
N/A	GND	J9	
N/A	GND	E9	
N/A	GND	A9	
N/A	GND	BB5	
N/A	GND	AV5	
N/A	GND	AP5	
N/A	GND	AK5	
N/A	GND	AF5	
N/A	GND	AC5	
N/A	GND	Y5	
N/A	GND	U5	
N/A	GND	N5	
N/A	GND	J5	
N/A	GND	E5	
N/A	GND	A5	
N/A	GND	BA3	
N/A	GND	B3	
N/A	GND	BA2	
N/A	GND	AY2	
N/A	GND	C2	
N/A	GND	B2	
N/A	GND	AV1	
N/A	GND	AP1	
N/A	GND	AK1	